



Application No. 09/755,282

March 04, 2003

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TO: Commissioner of Patents and Trademarks
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FROM: George O. Saile, Reg. No. 19,572
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SUBJECT: Serial #: 09/755,282
File Date: 01/08/01
Inventor: CHEN, SHENG-HSIUNG
Examiner: MITCHELL, JAMES M.
Art Unit: 2827
Title: METHOD OF IMPROVING COPPER PAD ADHESION

RESPONSE TO FINAL OFFICE ACTION

This is in response to the final office action dated
December 04, 2002, Paper No. 8. Please amend the above
identified Divisional Application for patent as follows:

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited
with the United States Postal Service as first class mail in an
envelope addressed to: Commissioner of Patents and Trademarks,
Washington, D.C. 20231 on March 4, 2003.

Signature

Date: MAR 4, 2003

Stephen B. Ackerman, Reg. No. 37,761

AMENDED CLAIMS (UNMARKED VERSION):

34. (AMENDED) A bond pad structure, comprising:
- a semiconductor substrate;
 - a plurality of conductive bond pads, comprising interlocking grid structures, formed over said semiconductor substrate;
 - a passivating layer formed over said bond pads, having multiple openings to each said bond pads;
 - a barrier layer formed over said passivating layer and in said openings;
 - a conducting pad formed over each said bond pad and over said barrier layer, whereby an upper surface of said conductive pad provides improved adhesion for subsequently formed bonds.